

ABSTRACT

[Abstract]

[Problem to be Solved]

To provide a measuring device preferable to enhance capability of pickup processing when picking up each chip of a plate-shaped member individually separated into a form of chips.

[Solution]

A semiconductor wafer 4 as a plate-shaped member supported by a support member H which is consisted of an adhesive sheet 3 and a ring frame 2, the adhesive sheet is stuck to an opening of the ring frame 2, and individually separated into a form of chips by cutting is set as a measurement target; an image processing unit 5 measures a chip interval G and a misalignment angle θ , and measurement data D of them is sent from the image processing unit 5 to a host computer 6, and stored in storage means 12 of the host computer 6; and based on the chip interval G and the misalignment angle θ stored in the storage means 12, position recognition processing at the time of confirming the position of a chip with a recognition unit of a pickup device, for example, a camera, and correction processing of aligning the position of a collet for pickup with the recognized position can be carried out in the next step.

[Selected Drawing] Figure 1